



Fermi National Accelerator Laboratory

General Information for Manufacture of Printed Circuit Boards

Note: All dimensions in inches unless specified

TOF CLOCK TRANSLATOR	Board Name
10	Quantity
2 signal, 2 power	Board Type (# signal layers - # power layers)
Not less than 63 mils	Board Thickness and Tolerance
7.125 x 9.000 inches	Board Dimensions and shape
SMOBC	Finish SMOBC (solder mask over bare copper)
HASL	Plating HASL (hot air solder leveling)
1	Cu Weight outer layers (ounces per square inch)
1	Cu Weight inner layers (ounces per square inch)
None	Number of gold contacts/side
10 mils	Minimum Trace width & tolerance
6 mils	Minimum Trace clearance & tolerance
Top and bottom	Solder Mask (top & bottom – top only)
1pi	Solder Mask Type (wet/dry/LPI)
Top and bottom	Silk Screen (top & bottom – top only - white)
yes	Testing Required (yes/no/specify)
~75 top and ~175 bottom	Number of Surface mount pads TOP/BOT (only needed for testing)
248	Number of Through Holes
7	Number of Drill Sizes
13 mils	Smallest Hole
130 mils	Largest Hole
None	Number of Blind Vias
None	Number of Buried Vias
100 ohm differential traces on bottom layer: 16 mil width, 6 mil separation.	Controlled Impedance (yes/no/specify)
-----	Physical Board Stackup
TOP	Top layer name
POWER	Inner layer
GND	Inner layer
BOTTOM	Bottom layer name
Gerber files	Material Supplied (Film/gerber files/modem/ect)
5/10 days	Required Delivery
	Special NOTES
Matthew Jones – 630-840-8410 Tom Wesson – 630-840-2948	Technical Contact Personnel and phone number

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